

## PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Seung Wook Yoon</td> <td>02/21/2013</td> </tr> <tr> <td>Jose A. Caparas</td> <td>02/21/2013</td> </tr> <tr> <td>Yaojian Lin</td> <td>02/21/2013</td> </tr> <tr> <td>Pandi C. Marimuthu</td> <td>02/21/2013</td> </tr> </tbody> </table>		Name	Execution Date	Seung Wook Yoon	02/21/2013	Jose A. Caparas	02/21/2013	Yaojian Lin	02/21/2013	Pandi C. Marimuthu	02/21/2013
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Seung Wook Yoon	02/21/2013										
Jose A. Caparas	02/21/2013										
Yaojian Lin	02/21/2013										
Pandi C. Marimuthu	02/21/2013										
RECEIVING PARTY DATA											
Name:	STATS ChipPAC, Ltd.										
Street Address:	10 Ang Mo Kio Street 65										
Internal Address:	#05-17/20 Techpoint										
City:	Singapore										
State/Country:	SINGAPORE										
Postal Code:	569059										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13772683</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13772683						
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Application Number:	13772683										
CORRESPONDENCE DATA											
Fax Number:	4804999456										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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ATTORNEY DOCKET NUMBER:	2515.0396										
NAME OF SUBMITTER:	Robert D. Atkins										

OP \$40.00 13772683

Total Attachments: 4

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ASSIGNMENT AND AGREEMENT

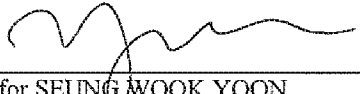
For good and valuable consideration, the receipt of which is hereby acknowledged, I, SEUNG WOOK YOON of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD FOR FORMING A LOW PROFILE EMBEDDED WAFER LEVEL BALL GRID ARRAY MOLDED LASER PACKAGE (EWLB-MLP), which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0396 and in U.S. Provisional Application No. 61/606,327, filed March 2, 2012, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

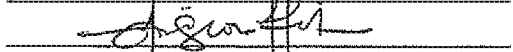


Signature for SEUNG WOOK YOON

Witnessed on this date:

21 FEB. 2013

Signature of Witness:



Printed Name of Witness:

DIOSCORO MERILO

Address of Witness:

5 YISHUN STREET 23  
SINGAPORE 768442

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, JOSE A. CAPARAS of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD FOR FORMING A LOW PROFILE EMBEDDED WAFER LEVEL BALL GRID ARRAY MOLDED LASER PACKAGE (EWLB-MLP), which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0396 and in U.S. Provisional Application No. 61/606,327, filed March 2, 2012, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

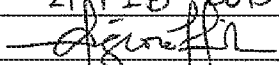
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\_\_\_\_\_  
Signature for JOSE A. CAPARAS

Witnessed on this date: 21 FEB 2013  
Signature of Witness:   
Printed Name of Witness: DISCORO MERILO  
Address of Witness: 5 YISHUN STREET 23  
SINGAPORE 768442

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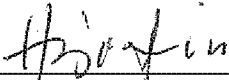
For good and valuable consideration, the receipt of which is hereby acknowledged, I, YAOJIAN LIN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD FOR FORMING A LOW PROFILE EMBEDDED WAFER LEVEL BALL GRID ARRAY MOLDED LASER PACKAGE (EWLB-MLP), which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0396 and in U.S. Provisional Application No. 61/606,327, filed March 2, 2012, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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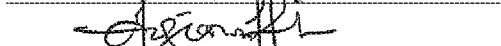


\_\_\_\_\_  
Signature for YAOJIAN LIN

Witnessed on this date:

24 FEB 2013

Signature of Witness:



Printed Name of Witness:

DIOSCOPO MERILO

Address of Witness:

5 YUSHUN STREET 23

SINGAPORE 768442

ASSIGNMENT AND AGREEMENT

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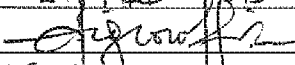
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Signature for PANDI C. MARIMUTHU

Witnessed on this date: 21 FEB 2013  
Signature of Witness:   
Printed Name of Witness: DIOSCORO MERILO  
Address of Witness: 5 YISHUN STREET 23  
SINGAPORE 768442